

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. KOMATSU, et al.
Serial No.: 10/594,548
Filed: SEPTEMBER 27, 2006
For: HEAT-RESISTANT PHOTSENSITIVE RESIN
COMPOSITION, METHOD FOR FORMING PATTERN USING
THE COMPOSITION, AND ELECTRONIC PART
Group AU: 1795
Examiner: John S. Y. Chu
Confirm. No.: 3540

AMENDMENT

Mail Stop: AMD - FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

January 26, 2009

Sir:

In response to the Office Action mailed September 25, 2008, the period for response having been extended for one (1) month by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.